Jackson Anderson

Curriculum Vitae, April 2025

33 Colchester Ave Burlington, VT 05405 USA ☑ Jackson.Anderson@uvm.edu in JAndersonEE Anderson419

Education

- 2023 Ph.D, Electrical and Computer Engineering, Purdue University, Lafayette, IN Dissertation: "CMOS Integrated Resonators and Emerging Materials for MEMS Applications."
- 2017 MS, Microelectronic Engineering, Rochester Institute of Technology, Rochester, NY Thesis: "Measurement of Ferroelectric Films in MFM and MFIS Structures."
- 2015 **BS, Microelectronic Engineering**, Rochester Institute of Technology, Rochester, NY

Professional Appointments

2023-Present Research Assistant Professor, Electrical and Biomedical Engineering, University of Vermont and State Agricultural College, Burlington, VT

Journal Publications

- [1] A. Charnas, J. Anderson, J. Zhang, D. Zheng, D. Weinstein, and P. D. Ye, "Ultrathin indium oxide thin-film transistors with gigahertz operation frequency," IEEE Transactions on Electron Devices, vol. 70, no. 2, pp. 532-536, Feb. 2023, ISSN: 1557-9646. DOI: 10.1109/TED.2022.3231226.
- [2] U. Rawat, J. D. Anderson, and D. Weinstein, "Design and applications of integrated transducers in commercial CMOS technology," Frontiers in Mechanical Engineering, vol. 8, 2022, ISSN: 2297-3079.
- [3] **J. Anderson**, Y. He, B. Bahr, and D. Weinstein, "Integrated acoustic resonators in commercial fin field-effect transistor technology," Nature Electronics, vol. 5, no. 9, pp. 611–619, Sep. 2022, ISSN: 2520-1131. DOI: 10.1038/s41928-022-00827-6.
- [4] C. Huang, J. Anderson, S. Peana, X. Chen, S. Ramanathan, and D. Weinstein, "Perovskite nickelate actuators," Journal of Microelectromechanical Systems, pp. 1-6, 2021, ISSN: 1941-0158. DOI: 10.1109/JMEMS.2021.3067189.
- [5] M. Restaino, N. Eckman, A. T. Alsharhan, et al., "In situ direct laser writing of 3d graphene-laden microstructures," Advanced Materials Technologies, vol. 6, no. 8, p. 2100222, 2021, ISSN: 2365-709X. DOI: 10.1002/admt.202100222.

[6] J. D. Anderson, J. Merkel, D. MacMahon, and S. K. Kurinec, "Evaluation of si:HfO2 ferroelectric properties in MFM and MFIS structures," *IEEE Journal of the Electron Devices Society*, vol. 6, pp. 525–534, 2018. DOI: 10.1109/JEDS. 2018.2826978.

Conference Proceedings

- [1] U. Rawat, **J. Anderson**, and D. Weinstein, "Large-signal analysis and modeling of CMOS-MEMS ferroelectric resonators," presented at the Hilton Head Sensors and Actuator Workshop, 2022, p. 1.
- [2] D. Zheng, A. Charnas, **J. Anderson**, *et al.*, "First demonstration of BEOL-compatible ultrathin atomic layer-deposited InZnO transistors with GHz operation and record high bias-stress stability," in *2022 International Electron Devices Meeting (IEDM)*, Dec. 2022, pp. 4.3.1–4.3.4. DOI: 10.1109/IEDM45625.2022. 10019452.
- [3] A. Charnas, **J. Anderson**, J. Zhang, D. Zheng, D. Weinstein, and P. D. Ye, "Record RF performance of ultra-thin indium oxide transistors with buried-gate structure," in *2022 Device Research Conference (DRC)*, Jun. 2022, pp. 1–2. DOI: 10.1109/DRC55272.2022.9855782.
- [4] **J. Anderson** and D. Weinstein, "PyMeasRF: Automating RF device measurements using python," Jul. 23, 2019. DOI: 10.25080/Majora-7ddc1dd1-014.

Grants and Fellowships

- Pending **NSF**, *PI*, Equipment: MRI Track 1: Acquisition of a Two-Photon Printer for Engineered Materials Research, \$876,840
- 2024-Present **NSF**, *PI*, ERI: Leveraging 2D Ferroelectric Semiconductors Towards Acoustoelectric Circulators, \$199,980
- 2024-Present **NSF**, *Sr. Personnel*, Bridging Microelectronics Education Gap in Rural State through Partnerships with K-12 School Science Teachers, 2024 Supplement to RII Track-2 FEC: Advancing Research Towards Industries of the Future to Ensure Economic Growth for EPSCoR Jurisdictions Advanced Wireless Integration with Infrastructure System, \$294,949

Awards and Honors

- 2016 NSF Graduate Research Fellowship, Honorable Mention
- 2016 RIT Turkman Scholar
- 2015 Tau Beta Pi Stabile Scholar

Invited Talks

2024 **Beilstein Symposium on Sensing with Mechanical Systems**, Ferroelectric Materials for Reprogrammable and CMOS-Integrated Transducers

Teaching Experience

University of Vermont

Instructor IC Fabrication (Fall '24)

Instructor Semiconductor Materials and Devices (Spring '24, '25)

Co-Instructor IC Fabrication [Lab] (Fall '23)

Purdue University

TA Electromagnetics (Fall '21 [In-Person])
Rochester Institute of Technology

TA Microelectronic Engineering Senior Design (Fall '16/Spring '17)

TA CMOS Processing (Spring '15/Fall '16)

TA Introduction to Microelectronic Engineering (Fall '15)

Research Experience

University of Vermont

- 2024-Present Acoustoelectric Interactions in In2Se3 towards RF Circulators
- 2024-Present Commercially Integrable Gallium Nitride Resonators
- 2023-Present Multidisciplinary Semiconductor Curriculum Development

Purdue University, HybridMEMS Lab

- 2022-2023 Van der Waals MEMS Resonators
- 2017-2022 Commercially-Integrated finFET Acoustic Resonators
- 2019-2020 Nickelate-Based MEMS Actuators
- 2018-2019 Measurement of Injection Locking in Colpitts Oscillators

Rochester Institute of Technology

- 2014-2017 Ferroelectric HfO2 Characterization
 - 2016 Polysilicon Microbolometer Design and Fabrication

Professional Service

2025 **Review Panelist**. National Science Foundation

- 2019-2022 **Contributor**, scikit-rf
 - 2021 Manuscript Review, IEEE Journal of the Electron Devices Society
 - 2021 Manuscript Review, Frontiers in Materials
 - 2016 **Conference Volunteer**, Emerging Technologies: Communications, Microsystems, Optoelectronics, Sensors

College & Departmental Service

- 2025 Admitted Student Visit Days, Organize lab visit for ASV events to highlight semiconductor learning opportunities at UVM to prospective engineering and science students
- 2024-Present **Certificate Research Advisor**, Serve as technical advisor in the area of semiconductor materials and devices for eight undergraduate student research projects/project proposals.
- 2024-Present **Project Advisor**, Work with two part-time EE graduate students to define and execute master's projects specialized to their interests
- 2024-Present **Committee Member**, Serve as part of ten PhD and MS students' exams (defense, comprehensive, and/or qualifying) in Electrical Engineering and Material Science programs.

Other Publications

- [1] **J. Anderson**. "Skrf network viewer," Plotly Dash Application Gallery. (), [Online]. Available: https://dash.gallery/dash-skrf-viewer/ (visited on 04/16/2023).
- [2] U. Rawat, **J. Anderson**, and D. Weinstein, *Large-signal behavior of ferroelectric micro-electromechanical transducers*, Apr. 12, 2023. DOI: 10.48550/arXiv. 2304.05975. arXiv: 2304.05975 [physics].
- [3] A. Arsenovic, J. Hillairet, **J. Anderson**, *et al.*, "Scikit-rf: An open source python package for microwave network creation, analysis, and calibration [speaker's corner]," *IEEE Microwave Magazine*, vol. 23, no. 1, pp. 98–105, Jan. 2022, ISSN: 1557-9581. DOI: 10.1109/MMM.2021.3117139.
- [4] J. C. Damle, J. Anderson, M. Storey, and D. Weinstein, "Automated measurement of acoustoelectric RF MEMS for wireless communication applications," Purdue SURF Symposium, p. 9, 2021.
- [5] H.-M. Tran, **J. Anderson**, and D. Weinstein, "Modeling ferroelectric domain switching kinetics," *Purdue SURF Symposium*, p. 3, 2020.
- [6] **J. Anderson**, "Ferroelectric hafnium dioxide thin films," *Annual Microelectronic Engineering Conference*, May 1, 2015.

Professional Skills

Programming Python, MATLAB, Perl, C

Fabrication CMOS Processing, Electron Beam Lithography, Design of Experiments, Soldering,

Hardware Assembly

Metrology On-wafer Electrical Probing [S-Parameter, IV, CV, PV], Circuit Test, AFM,

Ellipsometry, Reflectometry, SEM, FIB, EDS

Simulation COMSOL, Silvaco Atlas, Silvaco Athena, SLURM

EDA Keysight ADS, Cadence Virtuoso, Spectre, KiCad, LTSpice

Design Fusion 360, Blender, Affinity Designer, GNU Image Manipulation Program

Community Outreach

2025 Developing materials for summer workshop training K-12 teachers in microelectronics concepts.

2019 **Imagination Station**

Demonstrate cardiac anatomy of cow hearts to K-12 students at Halloween science event

2015-2017 **Imagine RIT**

Explain microelectronics processing and MEMS technologies at STEM festival attended by thousands.

Languages

English Native - C2

ASI Basic - A1

French Basic - A1

Professional Memberships

2019-Present IEEE Electron Devices Society

2019-Present IEEE Ultrasonics, Ferroelectrics, and Frequency Control Society

Member

2014-Present IEEE

Member